SLRS005 – SEPTEMBER 1986 – REVISED MAY 1990

- 1-A Output Current Capability Per Driver
- Pulsed Current 2-A Driver
- Wide Supply Voltage Range: 4.5 V to 36 V
- Separate Input-Logic Supply
- NE Package Designed for Heat Sinking
- Thermal Shutdown
- Internal ESD Protection
- High-Noise-Immunity Inputs
- Functional Replacement for SGS L293

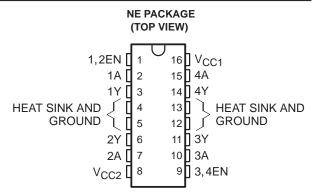
description

The L293 is a quadruple high-current half-H driver designed to provide bidirectional drive currents of up to 1 A at voltages from 4.5 V to 36 V. It is designed to drive inductive loads such as relays, solenoids, dc and bipolar stepping motors, as well as other high-current/high-voltage loads in positive-supply applications.

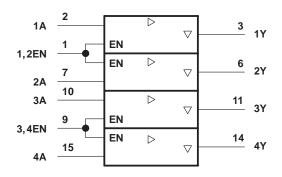
All inputs are TTL compatible. Each output is a complete totem-pole drive circuit with a Darlington transistor sink and a pseudo-Darlington source. Drivers are enabled in pairs with drivers 1 and 2 enabled by 1,2EN and drivers 3 and 4 enabled by 3,4EN. When an enable input is high, the associated drivers are enabled and their outputs are active and in phase with their inputs. When the enable input is low, those drivers are disabled and their outputs are off and in a high-impedance state. With the proper data inputs, each pair of drivers form a full-H (or bridge) reversible drive suitable for solenoid or motor applications.

External high-speed output clamp diodes should be used for inductive transient suppression. A V_{CC1} terminal, separate from V_{CC2} , is provided for the logic inputs to minimize device power dissipation.

The L293 is designed for operation from 0° C to 70° C.

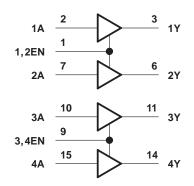


logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC publication 617-12.

logic diagram



FUNCTION TABLE (each driver)

INP	OUTPUT	
Α	EN	Y
Н	Н	Н
L	Н	L
Х	L	Z

H = high-level, L = low-level,

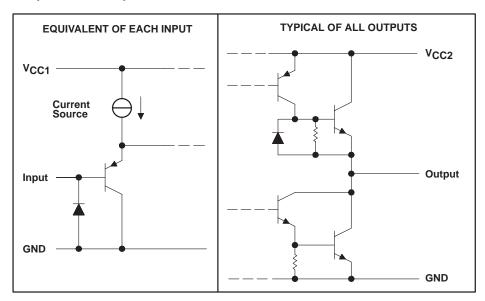
X = irrelevant, Z = high-impedance (off)

In the thermal shutdown mode, the output is in the high-impedance state regardless of the input levels.



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schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC1} (see Note 1)	36 V
Output supply voltage range, V _{CC2}	
Input voltage range, V ₁	7 V
Output voltage range, V _O –3 V to V _{CC2} +	- 3 V
Peak output current, I _O (nonrepetitive, t ≤ 5 ms)	±2 A
Continuous output current, I _O	±1 A
Continuous total dissipation at (or below) 25°C free-air temperature (see Notes 2 and 3) 2075	mW
Continuous total dissipation at 80°C case temperature (see Note 3)	mW
Operating case or virtual junction temperature range, T _A –40°C to 15	50°C
Storage temperature range, T _{stq} –65°C to 15	50°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	30°C

NOTES: 1. All voltage values are with respect to the network ground terminal.

- 2. For operation above 25°C free-air temperature, derate linearly at the rate of 16.6 mW/°C.
- 3. For operation above 25°C case temperature, derate linearly at the rate of 71.4 mW/°C. Due to variations in individual device electrical characteristics and thermal resistance, the built-in thermal overload protection may be activated at power levels slightly above or below the rated dissipation.

recommended operating conditions

		MIN	MAX	UNIT
Logic supply voltage, V _{CC1}		4.5	7	V
Output supply voltage, V _{CC2}			36	V
High-level input voltage, VIH	V _{CC1} ≤ 7 V	2.3		V
	V _{CC1} ≥ 7 V	2.3	7	
Low-level output voltage, V _{IL}		-0.3	1.5	V
Operating free-air temperature, T _A		(70	°C

The algebraic convention, in which the least positive (most negative) designated minimum, is used in this data sheet for logic voltage levels.



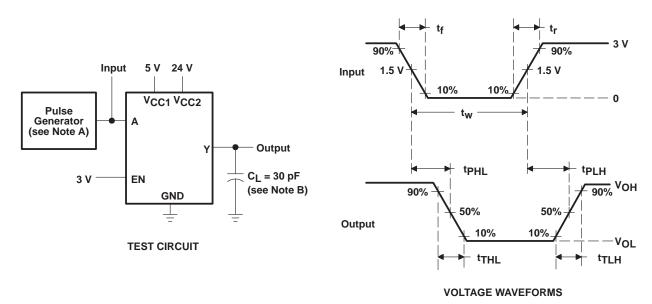
electrical characteristics, V_{CC1} = 5 V, V_{CC2} = 24 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT		
VOH	High-level output voltage		I _{OH} = -1 A		V _{CC2} -1.8	V _{CC2} -1.4		V	
VOL	V _{OL} Low-level output voltage		I _{OL} = 1 /	I _{OL} = 1 A		1.2	1.8	V	
I _{IH} High-lo	High level input groups	Α	V _I = 7 V			0.2	100	μΑ	
	High-level input current	EN				0.2	±10		
I	I a la distribuit a const	А	V 0			-3	-10		
'IL	IIL Low-level input current		V _I = 0			-2	-100	μΑ	
				All outputs at high level		13	22		
ICC1 Logic supply current		IO = 0	I _O = 0 All outputs at low level		35	60	mA		
			All outputs at high impedance		8	24			
				All outputs at high level		14	24		
ICC2	Output supply current	supply current		All outputs at low level		2	6	6 mA	
				All outputs at high impedance		2	4		

switching characteristics, V_{CC1} = 5 V, V_{CC2} = 24 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output from A input				800		ns
tPHL	Propagation delay time, high-to-low-level output from A input	C _L = 30 pF, See Figure			400		ns
tTLH	Transition time, low-to-high-level output				300		ns
tTHL	Transition time, high-to-low-level output				300		ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics: $t_f \le 10$ ns, $t_f \le 10$ ns, $t_W = 10$ μ s, PRR = 5 kHz, $Z_O = 50$ Ω .

B. C_L includes probe and jig capacitance.

Figure 1. Test Circuit and Voltage Waveforms



APPLICATION INFORMATION

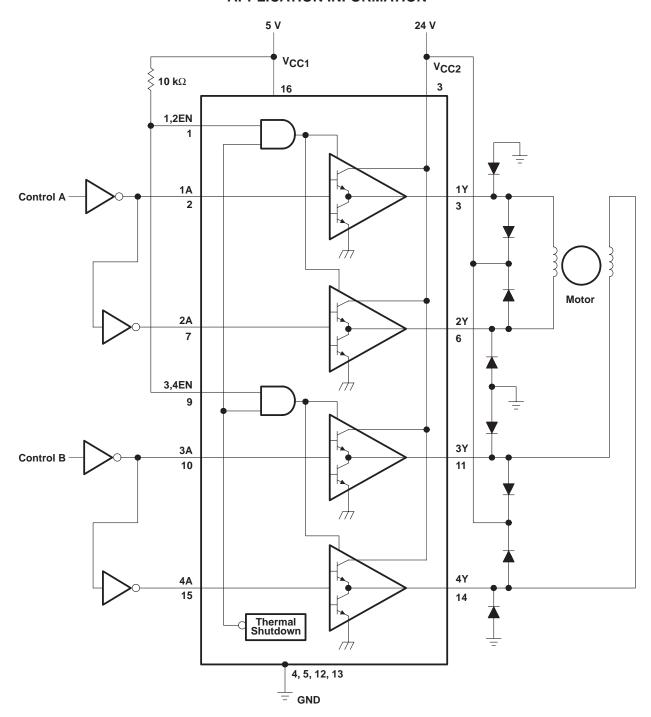


Figure 2. Two-Phase Motor Driver

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